

#### **OVLBx4C7 Series**

#### **Features:**

- High brightness with well-defined spatial radiation patterns
- UV-resistant epoxy lens
- Lead-frame material is iron alloy with tin plated leads
- No stand-offs



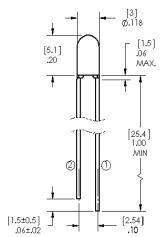
#### **Description:**

Each OVLBx4C7 series device is a high-intensity LED mounted in a clear plastic T-1 package. The LED provides a well-defined and even emission pattern. Its UV-resistant epoxy lens makes this device an optimal solution for outdoor applications.

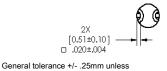
#### **Applications:**

- Pedestrian signals
- Signage and architectural lighting
- Backlighting
- Automotive
- Outdoor/indoor displays

Part Number	Material	Emitted Color	Intensity Typ. mcd	Lens Color
OVLBB4C7	InGaN	Blue	1800	Clear
OVLBG4C7	IIIGaN	Green	8400	Clear
OVLBR4C7	AllnGaP	Red	3700	Clear
OVLBY4C7	AllfigaP	Yellow	3700	Clear







① ANODE

② CATHODE

Dimensions are in Inches [MM]

DO NOT LOOK DIRECTLY
AT LED WITH
UNSHIELDED EYES OR
DAMAGE TO RETINA MAY

General Note

TT Electronics reserves the right to make changes in product specification without notice or liability. All information is subject to TT Electronics' own data and is considered accurate at time of going to print.

## **OVLBx4C7 Series**



#### **Electrical Specifications**

#### **Absolute Maximum Ratings** (T<sub>A</sub> = 25° C unless otherwise noted)

Storage Temperature Range		-40 ~ +100 °C
Operating Temperature Range		-40 ~ +100 °C
Reverse Voltage (Device not designed for reverse voltage applications)		5 V Max
Continuous Forward Current (Design of heat dissipation should be considered)	Blue, Green	25 mA
Continuous Forward Current (Design of heat dissipation should be considered)	Red, Yellow	50 mA
Peak Forward Current (10% Duty Cycle, 1 kHz)	Blue, Green	100 mA
Peak Forward Current (10% Duty Cycle, 1 kHz)	Red, Yellow	100 mA
Power Dissipation	Blue, Green	100 mW
Power Dissipation	Red, Yellow	120 mW
Current Linearity vs Ambient Temperature	Blue, Green	-0.29 mA/° C
Current Linearity vs Ambient Temperature	Red, Yellow	-0.72 mA/° C
LED Junction Temperature		125° C
Electrostatic Discharge Classification (JEDEC-JESD22-A114F)		Class 1C
Lead Soldering Temperature (4 mm away from the base of the epoxy bulb)		260° C / 3 seconds

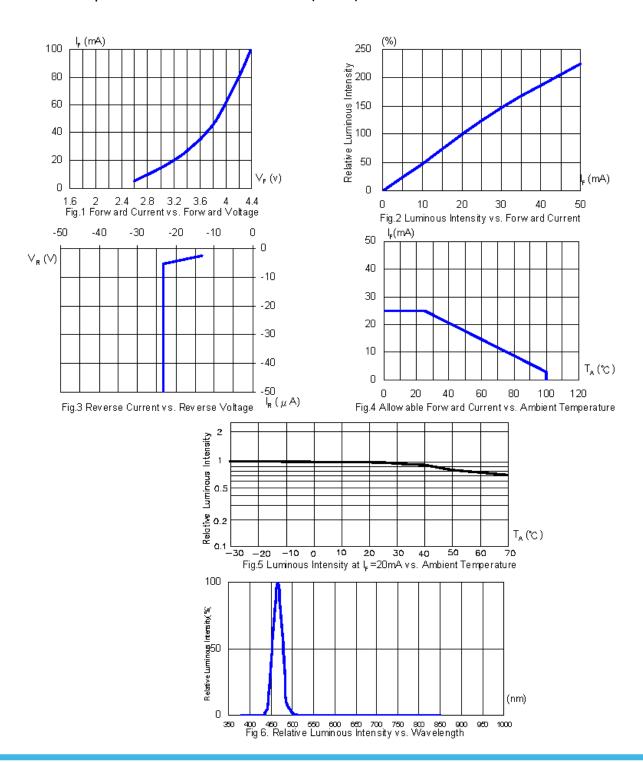
## Electrical Characteristics (T<sub>A</sub> = 25°C unless otherwise noted)

SYMBOL	PARAMETER	COLOR	MIN	TYP	MAX	UNITS	CONDITIONS	
I <sub>V</sub>		Blue	1135	1800		mcd		
	Luminous Intensity	Green	4360	8400			I <sub>F</sub> = 20 mA	
		Red	2225	3700				
		Yellow	2225	3700				
V <sub>F</sub>		Blue	2.6	2.2	4.0	V	I <sub>F</sub> = 20 mA	
	Forward Voltage	Green	2.6	3.2				
		Red	1.8	2.0	2.4			
		Yellow						
	Second County	Blue			10			
		Green					V - F V	
I <sub>R</sub>	Reverse Current	Red	10	μΑ	V <sub>R</sub> = 5 V			
		Yellow						
$\lambda_{D}$	Dominant Wavelength	Blue	460	470	475			
		Green	519	525	531	L = 20 mA		
		Red	620	623	630	nm	I <sub>F</sub> = 20 mA	
		Yellow	585	589	595			
20½H-H	50% Power Angle			45		deg	I <sub>F</sub> = 20 mA	

#### **OVLBx4C7** Series



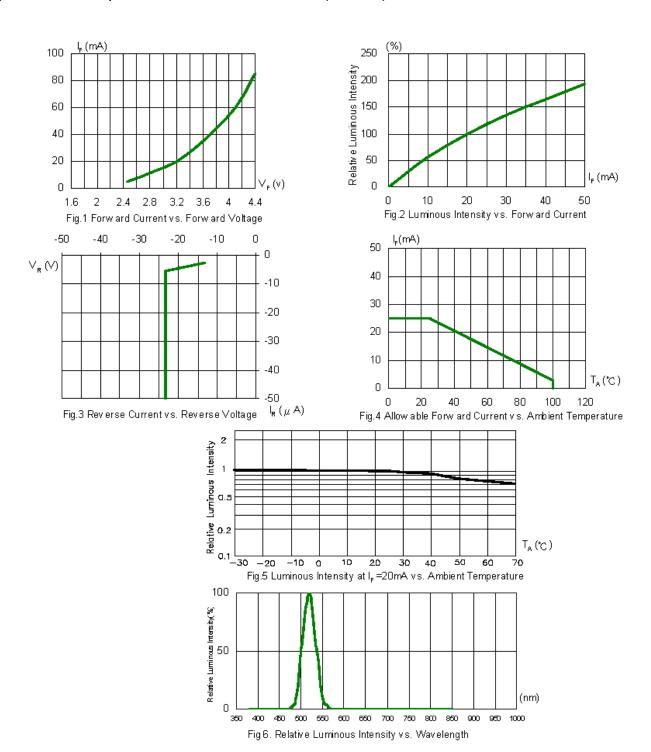
#### Typical Electro-Optical Characteristics Curves (BLUE)



#### **OVLBx4C7** Series



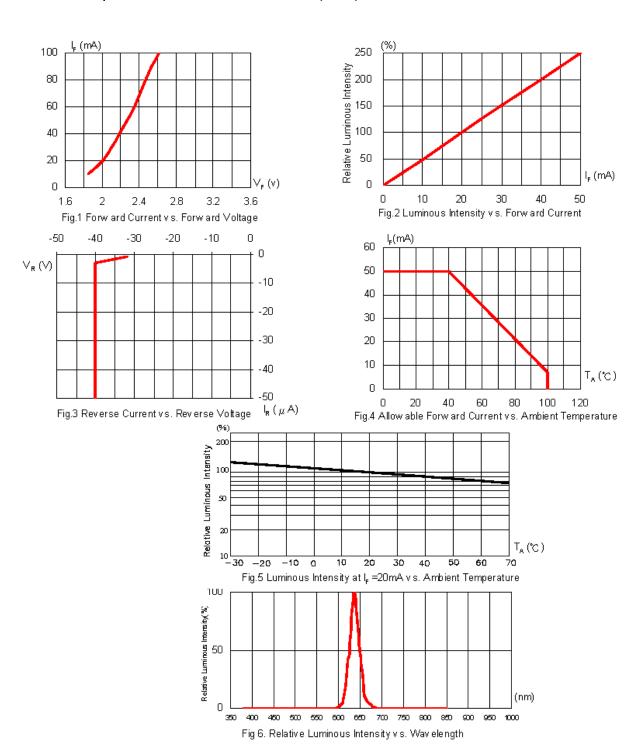
#### Typical Electro-Optical Characteristics Curves (GREEN)



#### **OVLBx4C7** Series



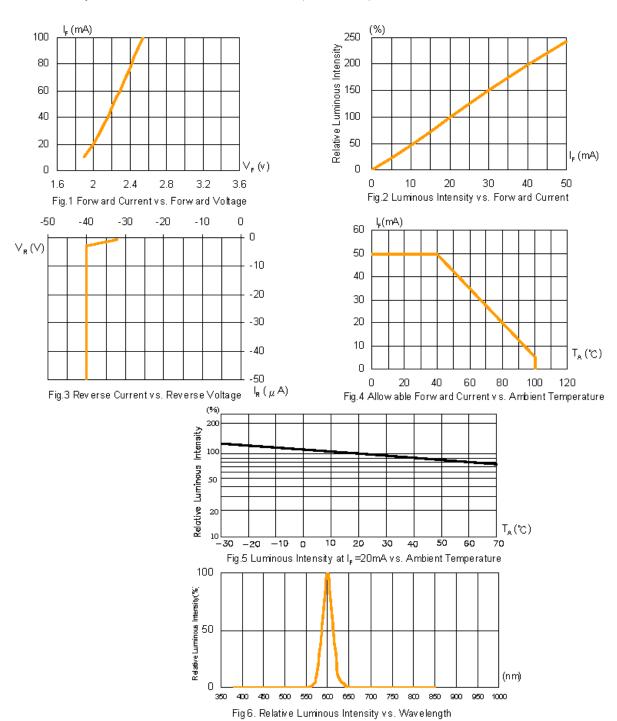
#### Typical Electro-Optical Characteristics Curves (RED)



#### **OVLBx4C7** Series



## Typical Electro-Optical Characteristics Curves (YELLOW)

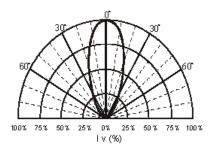


#### **OVLBx4C7** Series

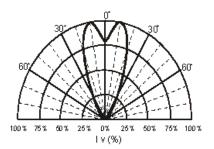


#### Beam Pattern:

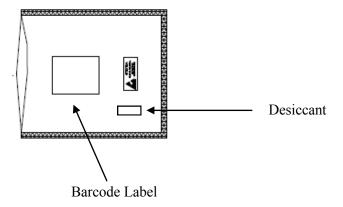
(Blue) and (Green)



(Red) and (Yellow)



#### Packaging: 500 pcs per bulk bag with desiccant



#### **OVLBx4C7 Series**



#### **Reliability Test**

Classi- fication	Test Item	Standard Test Method	Test Conditions	Duration	Unit	Acc / Rej Criteria	Result
Life Test	Operation Life Test (OLT)	MIL-STD-750D Method 1026.3	$T_A=25^{\circ}C$ , $I_F=30mA$ *	1000 Hrs	100	0 / 1	Pass
Environment Test	High Temperature Storage (HTS)	MIL-STD-750D Method 1032.1	T <sub>A</sub> =100°C	1000 Hrs	100	0 / 1	Pass
	Low Temperature Storage (LTS)	MIL-STD-750D Method 1032.1	T <sub>A</sub> =-40°C	1000 Hrs	100	0 / 1	Pass
	Temp. & Humidity with Bias (THB)	MIL-STD-750D Method 103B	T <sub>A</sub> =85°C , Rh=85% I <sub>F</sub> =20mA **	500 Hrs	100	0 / 1	Pass
	Thermal Shock Test (TST)	MIL-STD-750D Method 1056.1	0°C ~ 100°C 2min 2min	100 cycles	100	0 / 1	Pass
	Temperature Cycling Test (TCT)	MIL-STD-750D Method 1051.5	-40°C ~ 25°C ~ 100°C ~ 25°C 30min 5min 30min 5min	100 cycles	100	0 / 1	Pass
Mechanical Test	Solderability	MIL-STD-750D Method 2026.4	235±5°C → 5 sec	1 time	20	0 / 1	Pass
	Resistance to Soldering Heat	MIL-STD-750D Method 2031.1	260±5°C → 10 sec	1 time	20	0 / 1	Pass
	Lead Integrity	MIL-STD-750D Method 2036.3	Load 2.5N (0.25kgf) 0°~90°~0°, bend	3 times	20	0 / 1	Pass

Remark : (\*)  $\rm I_F$  =30mA for AlInGaP chip ;  $\rm I_F$  =20mA for InGaN chip

(\*\*)  $I_F = 20 \text{mA}$  for AlInGaP chip;  $I_F = 10 \text{mA}$  for InGaN chip

#### 2. Failure Criteria (T<sub>A</sub> =25°C):

Test Item	Symbol	Test Conditions	Criteria for Judgment			
	Symbol		Min.	Max.		
Luminous Intensity	$I_{V}$	I <sub>F</sub> =20 mA	LSL×0.7 **			
Voltage (Forward)	V <sub>F</sub>	I <sub>F</sub> =20 mA		USL×1.1 *		

(\*) USL : Upper Standard Level , (\*\*) LSL : Lower Standard Level